

Amendments to the Claims

The following listing of claims replaces all prior listings and versions of the claims in this application.

Please cancel claims 2, 10, 17 and 18 without prejudice or disclaimer.

1. (Currently Amended) A method of adhesion of conductive materials comprising (1) forming an adhesive surface having an adhesive resin layer on a conductive material by an electrodeposition step with an adhesive composition and (2) joining an adherend surface of an adhesion target to the adhesive surface having the adhesive resin layer obtained in (1), wherein (2) includes adhesion with heating and curing by heating, and
wherein the adhesive composition comprises a hydratable functional group- and unsaturated bond-containing cationic resin composition;

the adhesive composition is substantially incapable of generating any volatile matter in the heating for curing; drying is carried out between (1) and (2); and the drying is carried out such that the conductive material with an adhesive surface formed thereon is heated in a temperature range within which no curing reaction occurs.

2. (Canceled)

3. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the cationic resin composition is one allowing the formation, in the adhesive resin layer, of such chemical species activated by the electrode reaction caused by voltage application in the electrodeposition step as can promote the progress of the curing reaction.

4. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the hydratable functional group is a sulfonium group.

5. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the unsaturated bond is at least partly a propargyl carbon-carbon triple bond.

6. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the cationic resin composition has a sulfonium group content of 5 to 400 millimoles, a propargyl group content of 10 to 495 millimoles, and a total content of sulfonium and propargyl groups of not more than 500 millimoles, per 100 g of the solid matter in the cationic resin composition.

7. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the cationic resin composition has a sulfonium group content of 5 to 250 millimoles, a propargyl group content of 20 to 395 millimoles, and a total content of sulfonium and propargyl groups of not more than 400 millimoles, per 100 g of the solid matter in the cationic resin composition.

8. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the cationic resin composition has an epoxy resin as a skeleton.

9. (Original) The method of adhesion of conductive materials according to claim 8, wherein the epoxy resin is a novolak cresol epoxy resin or novolak phenol epoxy resin and has a number average molecular weight of 700 to 5,000.

10. (Canceled)

11. (Canceled)

12. (Currently Amended) The method of adhesion of conductive materials according to claim 1,

wherein the adherend surface is an adhesive surface having an adhesive resin layer.

13. (Currently Amended) The method of adhesion of conductive materials according to claim 1,

wherein the adhesion target is a conductive material and the adherend surface is an adhesive surface having an adhesive resin layer formed by an electrodeposition step of a conductive material with an adhesive composition.

14. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the conductive material is made of copper, aluminum, iron or an alloy mainly composed of these.

15. (Previously Presented) A laminate as obtained by the method of adhesion of conductive materials according to claim 1.

16. (Canceled)

17. (Canceled)

18. (Canceled)

19. (Previously Presented) The method of adhesion of conductive materials according to claim 3,

wherein the hydratable functional group is a sulfonium group.

20. (Currently Amended) The method of adhesion of conductive materials according to claim 2,

wherein the unsaturated bond is at least partly a propargyl carbon-carbon triple bond.

21. (Previously Presented) The method of adhesion of conductive materials according to claim 1,

wherein the adhesive resin layer becomes electrically insulative after the curing by heating.

22. (New) The method of adhesion of conductive materials according to claim 4, wherein the unsaturated bond is at least partly a propargyl carbon-carbon triple bond.

23. (New) The method of adhesion of conductive materials according to claim 1, wherein the drying is carried out by heating the conductive material within the temperature range of 50°C to 100°C.